- Three-State Outputs Interface Directly with System Bus
- 'LS257B and 'LS258B Offer Three Times the Sink-Current Capability of the Original 'LS257 and 'LS258
- Same Pin Assignments as SN54LS157, SN74LS157, SN54S157, SN74S157, and SN54LS158, SN74LS158, SN54S158, SN74S158
- Provides Bus Interface from Multiple Sources in High-Performance Systems

	AVERAGE PROPAGATION	TYPICAL
	DELAY FROM	POWER
	DATA INPUT	DISSIPATIONT
'LS257B	9 ns	55 mW
'LS258B	9 ns	55 mW
'S257	4.8 ns	320 mW
'S258	4 ns	280 mW

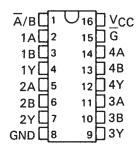
<sup>†</sup>Off state (worst case)

#### description

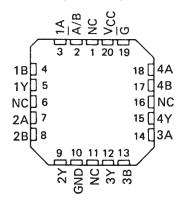
These devices are designed to multiplex signals from four-bit data sources to four-output data lines in busorganized systems. The 3-state outputs will not load the data lines when the output control pin  $(\overline{G})$  is at a high-logic level.

Series 54LS and 54S are characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C; Series 74LS and 74S are characterized for operation from 0°C to 70°C.

SN54LS257B, SN54S257, SN54LS258B, SN54S258 . . . J OR W PACKAGE SN74LS257B, SN74S257, SN74LS258B, SN74S258 . . . D OR N PACKAGE (TOP VIEW)



SN54LS257B, SN54S257, SN54LS258B, SN54S258 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection.

### **FUNCTION TABLE**

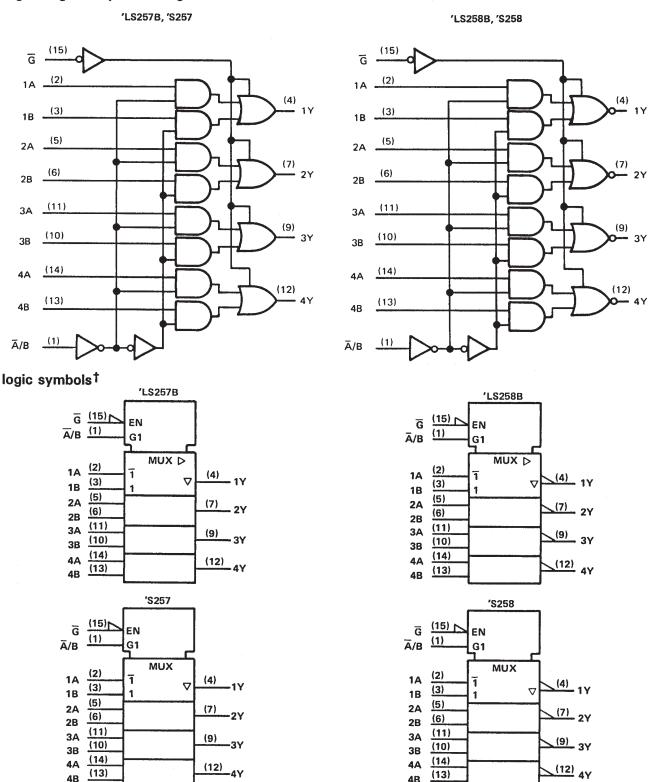
	INPUTS			OUTF	Y TU
OUTPUT CONTROL	SELECT	А	В	'LS257B 'S257	'LS258B 'S258
Н	Х	Х	Х	Z	Z
L	L,	L	Х	L	Н
L.	L	Н	Х	Н	L
L	Н	Х	L.	L	Н
L	Н	Х	Н	Н	L

H = high level, L = low level, X = irrelevant,

Z = high impedance (off)



### logic diagrams (positive logic)



<sup>&</sup>lt;sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

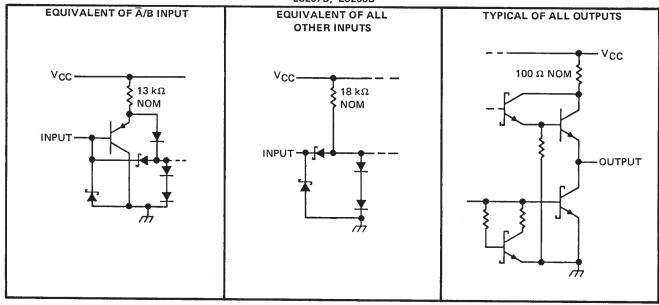


(13)

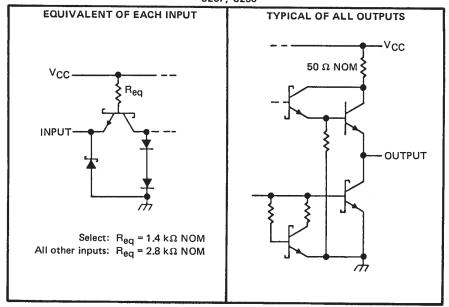
(13)4B

### schematics of inputs and outputs

#### 'LS257B, 'LS258B



'S257, 'S258



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: 'LS257B, 'LS258B Circuits	
'S257, 'S258 Circuits	5.5 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS', SN54S' Circuits	
	0°C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.



## SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SDLS148 - OCTOBER 1976 - REVISED MARCH 1988

### recommended operating conditions

			SN54LS'		SN74LS'			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2		<del></del>	V
VIL	Low-level input voltage			0.7			0.8	V
IOH	High-level output current		· ··	<b>– 1</b>	<u> </u>		- 2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TE	ST CONDITION	ust		SN54LS	3'		SN74LS	3'	
		•	ST CONDITION	40.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK		V <sub>CC</sub> = MIN,	1 <sub>1</sub> = 18 mA				- 1.5			- 1.5	V
V <sub>OH</sub>		V <sub>CC</sub> = MIN, I <sub>OH</sub> = MAX	V <sub>IH</sub> = 2 V,	VIL = MAX,	2.4	3.4		2.4	3.1	, ,	٧
VOL		VCC = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	<u> </u>
-02		VIL = MAX,		I <sub>OL</sub> = 24 mA		***************************************			0.35	0.5	٧
lozh		V <sub>CC</sub> = MAX,	V <sub>IH</sub> = 2 V,	V <sub>O</sub> = 2.7 V			20			20	μΑ
lozL		V <sub>CC</sub> - MAX,	$V_{1H} = 2 V$	V <sub>O</sub> = 0.4 V			20			- 20	μΑ
11		V <sub>CC</sub> = MAX,	V1 = 7 V				0.1			0.1	mA
ΊΗ		V <sub>CC</sub> = MAX,	V1 = 2.7 V				20			20	μΑ
l <sub>I</sub> L_		V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V				- 0.4			- 0.4	mA
los §		V <sub>CC</sub> = MAX,			- 30		- 130	- 30		- 130	mA
	All outputs high					8	12		8	12	
	All outputs low			'LS257B		12	18		12	18	1
loo	All outputs off	VMAY	Can Nata O			13	19		13	19	1
lcc	All outputs high	$V_{CC} = MAX,$	See NOTE 2			6	9		6	9	mA
	All outputs low			'LS258B		10	15		10	15	1
	All outputs off					11	16		11	16	1

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}C$ .

### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_{A} = 25^{\circ}\text{C}$ . $R_{I} = 667 \Omega$

PARAMETER	FROM	то	TEST CON	IDITIONS		'LS257	В		'LS258	В	
TATION LIET	(INPUT)	(OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Data	Any				8	13		7	12	
<sup>t</sup> PHL	Data	Ally				10	15		11	17	ns
<sup>t</sup> PLH	Select	Any	C <sub>L</sub> = 45 pF,	See Note 3		16	21		14	21	
tpHL			C[ - 45 pr,	See Note S		17	24		19	24	ns
<sup>t</sup> PZH	Output	Any			-	15	30		15	30	
<sup>t</sup> PZL	Control	City				19	30		20	30	ns
<sup>t</sup> PHZ	Output	Any	C <sub>L</sub> = 5 pF,	See Note 3		18	30		18	30	
<sup>t</sup> PLZ	Control		CL - 5 pr,	See Note 3		16	25		16	25	ns

¶tpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

tpzH = output enable time to high level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

tpzL = output enable time to low level

tpHZ = output disable time from high level

tpLZ = output disable time from low level



<sup>§</sup>Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

### recommended operating conditions

		SN54S'			SN745	,	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	CIVIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-2			6.5	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

							<b>'S257</b>			'S258		UNIT
	PARAME'	TER	TEST	CONDITIONS <sup>1</sup>	ī	MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	UNIT
VIH	High-level input	voltage				2			2			V
VIL	Low-level input						., .	0.8			0.8	V
VIK	Input clamp vol		V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				1.2			-1.2	V
	•		V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -1 mA	SN745'	2.7			2.7			v
VOH	High-level outpu	it voltage	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	SN54S'	2.4	3.4		2.4	3.4		,
			$V_{IL} = 0.8 V$ ,	IOH = MAX	SN74S'	2.4	3.2		2.4	3.2		
VOL	Low-level outpu	ıt voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V,	V <sub>1H</sub> = 2 V, I <sub>OL</sub> = 20 mA				0.5			0.5	٧
lozh	Off-state output	· ·	V <sub>CC</sub> = MAX, V <sub>O</sub> = 2.4 V	V <sub>IH</sub> = 2 V,				50			50	μА
lozL	Off-state output	· ·	V <sub>CC</sub> = MAX, V <sub>O</sub> = 0.5 V	V <sub>IH</sub> = 2 V,				-50			-50	μА
l <sub>1</sub>	Input current a	t maximum	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V	.,,			1			1	mA
	High-level	Sinput		07.1				100			100	μΑ
۱нн	input current	Any other	V <sub>CC</sub> = MAX,	, V <sub>1</sub> = 2.7 V				50			50	] "
	Low-level	S input		0.5.1/				-4			-4	mA
11L	input current	Any other	V <sub>CC</sub> = MAX	V I = 0.5 V				-2			-2	
los	Short-circuit ou	itput current§	V <sub>CC</sub> = MAX			-40		-100	-40		-100	mA
		All outputs high					44	68		36	56	1
ICC	Supply current	All outputs low	VCC = MAX	, See Note 2			60	93		52	81	mA
		All outputs off	]				64	99		56	87	

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

### switching characteristics, VCC = 5 V, $TA = 25^{\circ}\text{C}$ , $RL = 280 \Omega$

	FROM	то	TEST		'S257			'S258		UNIT
PARAMETER¶	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
tPLH	5-1-	A ===			5	7.5		4	6	ns
tPHL tPHL	Data	Any			4.5	6.5		4	6	]
tPLH	0.1	A	$C_L = 15  pF$ ,		8.5	15		8	12	ns
tPHL	Select	Any	See Note 3		8.5	15		7.5	12	113
tPZH	Output				13	19.5		13	19.5	ns
tPZL	Control	Any			14	21		14	21	1 "
tPHZ	Output	_	$C_L = 5 pF$ ,		5.5	8.5		5.5	8.5	200
t <sub>PLZ</sub>	Control	Any	See Note 3		9	14		9	14	ns

<sup>¶</sup>f<sub>max</sub> = Maximum clock frequency

 $t_{PZL} \equiv output$  enable time to low level  $t_{PHZ} \equiv output$  disable time from high level





<sup>‡</sup>All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25 ^{\circ}\text{C}$ .

Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

tpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

tpZH = output enable time to high level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-7603701VEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-7603701VFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
5962-7603701VFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
7603701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
7603701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
7603701FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
7603701FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
76038012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
76038012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
7603801EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
7603801EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
7603801FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
7603801FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
8002301EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
8002301EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
8002301FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
8002301FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





om 26-Sep-2005

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3</sup>
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free	CU NIPDAU	Level-NC-NC-NC





26-Sep-2005

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(</sup>
						(RoHS)		
SN74LS258BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS258BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S257DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S257DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S257NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S257NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S258DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S258DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S258N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S258N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS258BFK	ACTIVE	LCCC	FK	20	1	TBD		Level-NC-NC-NC
SNJ54LS258BFK	ACTIVE	LCCC	FK	20	1	TBD		Level-NC-NC-NC
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD		Level-NC-NC-NC
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD		Level-NC-NC-NC
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD		Level-NC-NC-NC



### PACKAGE OPTION ADDENDUM

26-Sep-2005

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp (3)
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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